

1 2 3 4 5 6 7 8

A

B

C

D

E

F

G

H

A

B

C

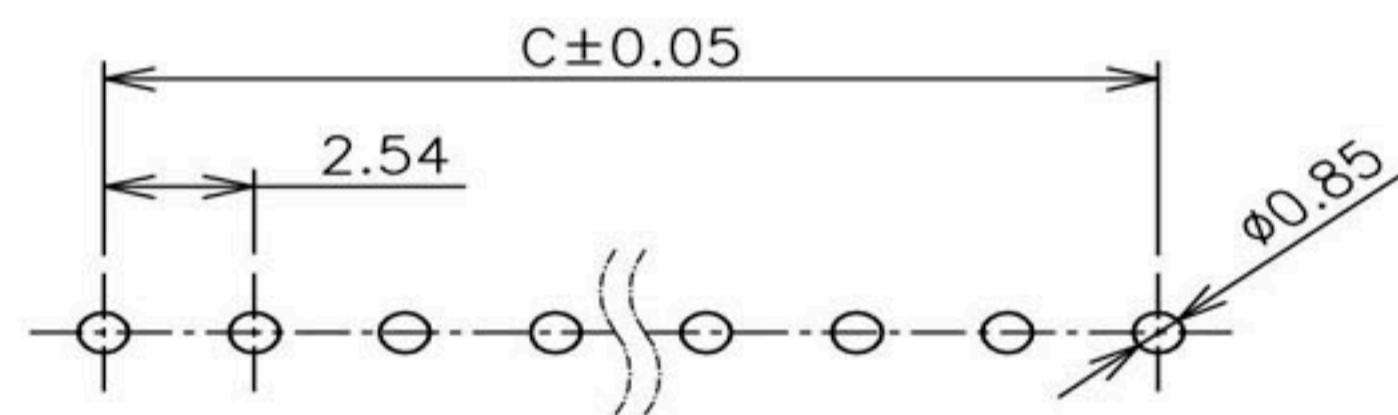
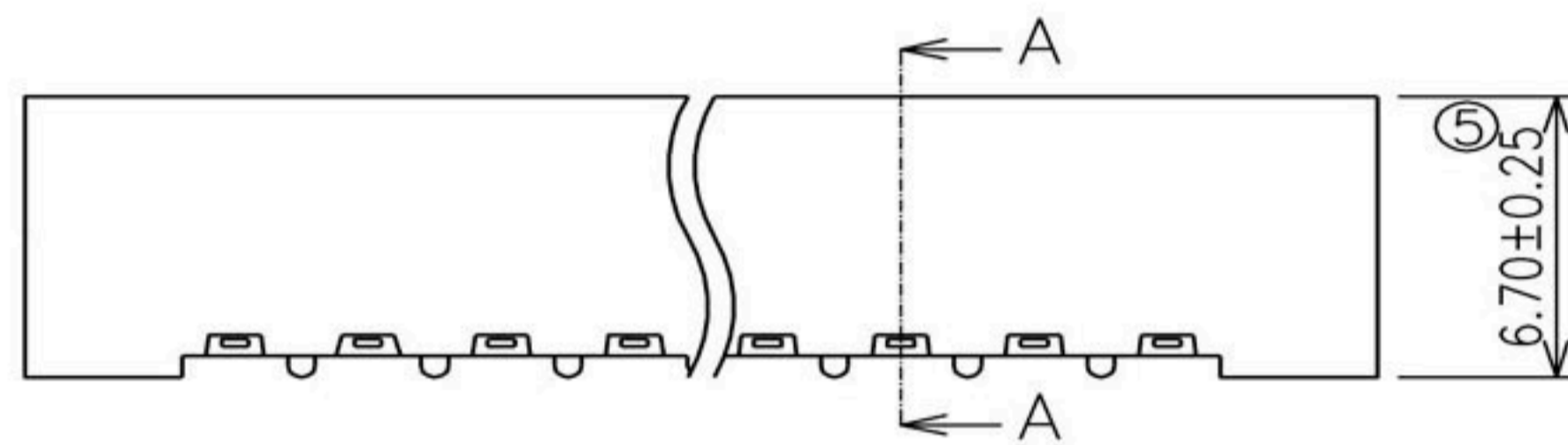
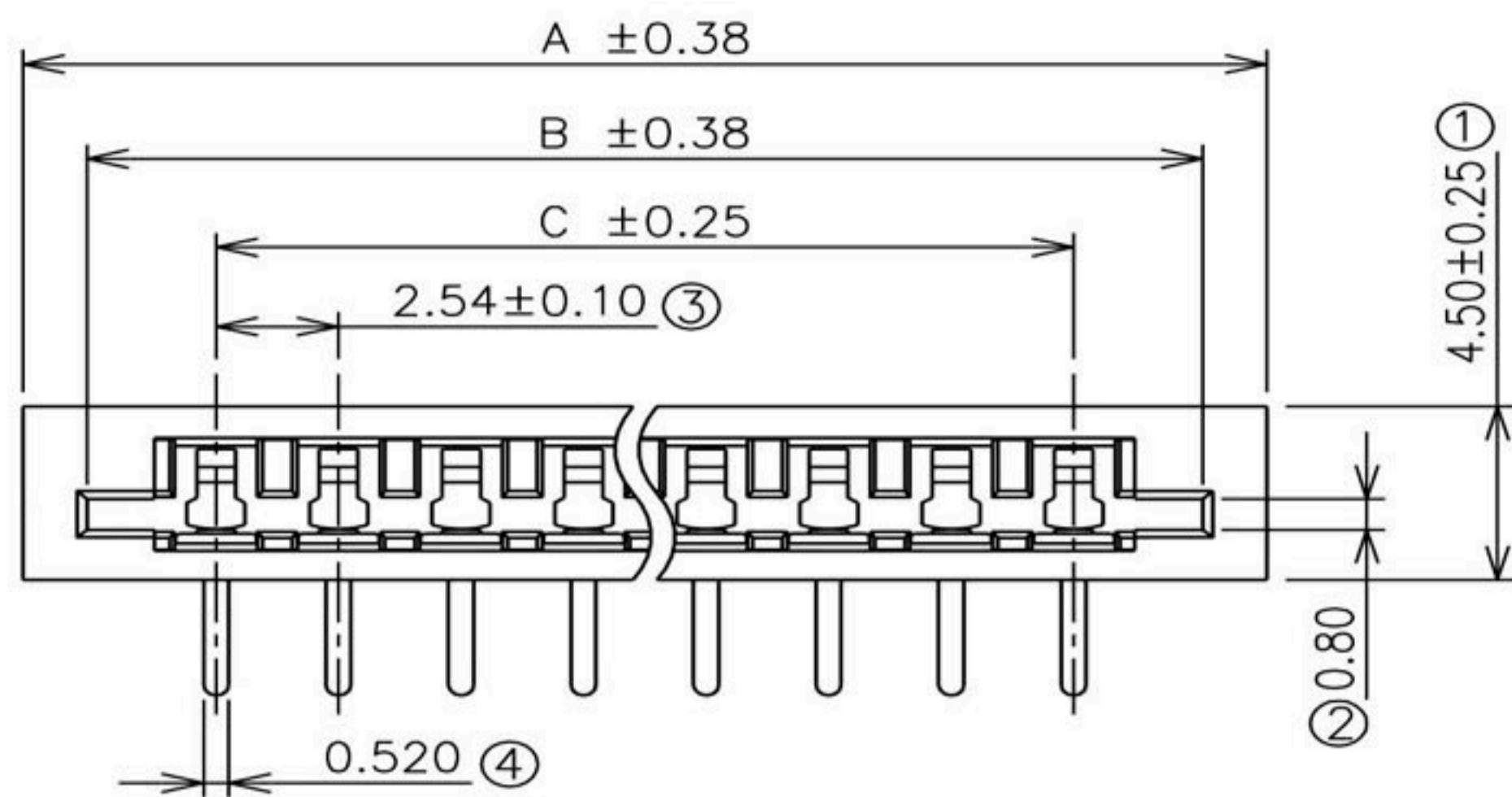
D

E

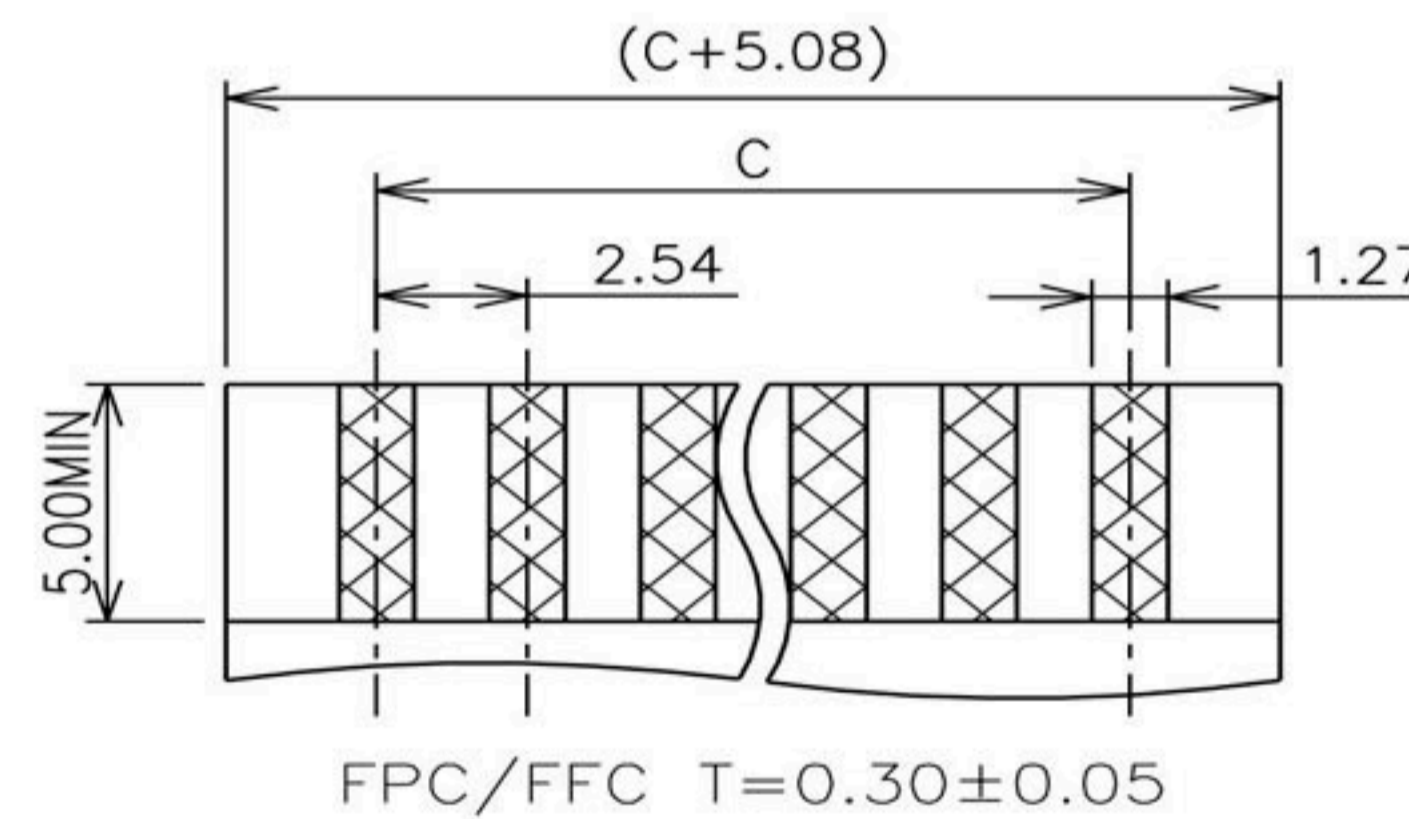
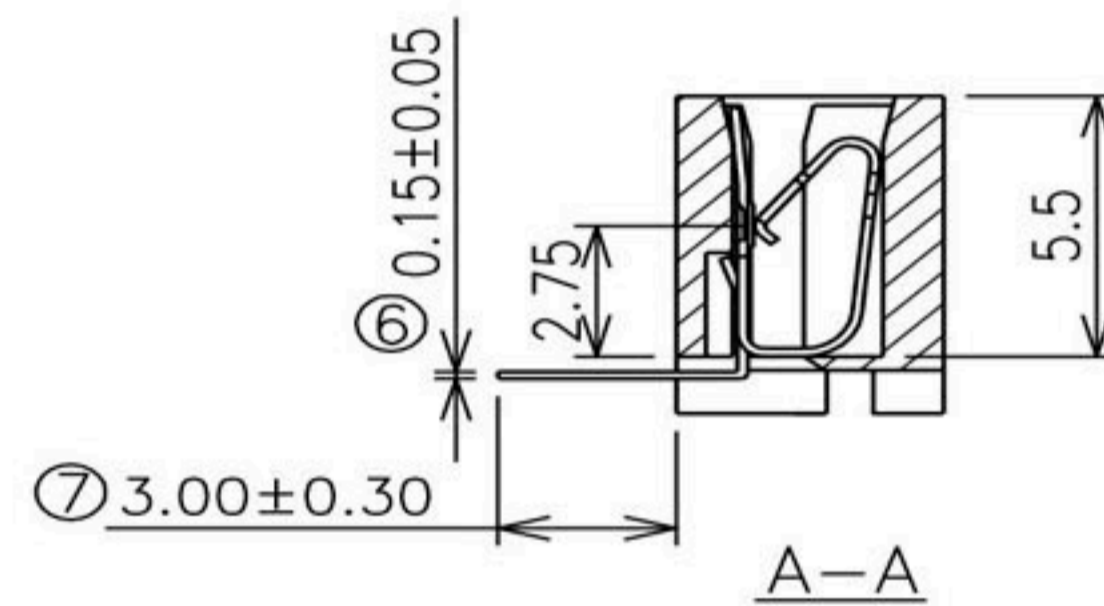
F

G

H



RECOMMENDED PCB LAYOUT



FPC/FFC T=0.30±0.05

NOTE:

■ MATERIAL

HOUSING: GLASS-REINFORCED THERMOPLASTIC UL 94V-0.
CONTACT: COPPER ALLOY.
PLATING: TIN PLATED OVER NICKEL

■ ELECTRICAL

CURRENT RATING: 3.0AMP.
DIELECTRIC WITHSTANDING VOLTAGE: 1000V AC MIN.
INSULATION RESISTANCE: 1000MΩ MIN.
CONTACT RESISTANCE: 30mΩ MAX.

■ ENVIRONMENTAL

TEMPERATURE RANGE: -25°C TO 85°C.

■ PART NO.

■ DIMENSION TABLE

Circuit	Dimension			Circuit	Dimension		
	A	B	C		A	B	C
2	10.54	8.43	2.54	20	56.26	54.15	48.26
3	13.08	10.97	5.08				
4	15.62	13.51	7.62				
5	18.16	16.05	10.16				
6	20.70	18.59	12.70				
7	23.24	21.13	15.24				
8	25.78	23.67	17.78				
9	28.32	26.21	20.32				
10	30.86	28.75	22.86				
11	33.40	31.29	25.40				
12	35.94	33.83	27.94				
13	38.48	36.37	30.48				
14	41.02	38.91	33.02				
15	43.56	41.45	35.56				
16	46.10	43.99	38.10				
17	48.64	46.53	40.64				
18	51.18	49.07	43.18				
19	53.72	51.60	45.72				

<p>RoHS Compliant</p>		<p>HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.</p>	
<p>APPD. 核准</p>		<p>TOLERANCE 容許公差</p> <p>.0 ±0.3 .00 ±0.2 ANG. ±</p>	<p>PART NAME 品名</p> <p>FFC/FPC NON-ZIF 2.54mm DUAL CONTACT XXP 90° TIN PLATING BLACK COLOR ROHS</p>
<p>DWG. 製圖</p> <p>Helen</p>	<p>SCALE 比例 參考</p>	<p>UNIT 單位 M M</p>	<p>PART NO. 料號</p> <p>C3900-XXDITB00R</p>
<p>DATE 制表日</p> <p>2022/8/16</p>	<p>PAGE 張數 1 OF 1</p>	<p>REV. 版本 C</p>	

1 2 3 4 5 6 7 8